

L Number	Hits	Search Text	DB	Time stamp
1	711	mirror and barrier and adhesive and die	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 07:47
2	14	mirror and barrier and adhesive and die and gan	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 07:47
3	2	(backside back-side rear) WITH (reflector reflective reflecting mirror) and barrier and adhesive and die and gan	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 07:51
4	0	(backside back-side rear) WITH (reflector reflective reflection reflecting mirror) and corrosion and die and gan	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 07:51
5	73	(backside back-side rear) WITH (reflector reflective reflection reflecting mirror) and corrosion and die	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 08:21
6	95	(backside back-side rear) WITH (reflector reflective reflection reflecting mirror) and corrosion and (solder barrier adhesive) and (die chip)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 08:29
7	56	((backside back-side rear) WITH (reflector reflective reflection reflecting mirror) and corrosion and (solder barrier adhesive) and (die chip)) not ((backside back-side rear) WITH (reflector reflective reflection reflecting mirror) and corrosion and die)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 08:43
8	19	5192626.URPN.	USPAT	2002/08/31 08:37
9	183	(uemura-toshiya\$ nagasaka-naohisa\$ hashimura-masaki\$ hirano-atsuo\$ tadano-Hiroshi\$ kachi-tetsu\$ howokawa-hideki\$).in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 08:45
11	4	(uemura-toshiya\$ nagasaka-naohisa\$ hashimura-masaki\$ hirano-atsuo\$ tadano-Hiroshi\$ kachi-tetsu\$ hosokawa-hideki\$).in. and corrosion	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 08:46
12	22	(uemura-toshiya\$ nagasaka-naohisa\$ hashimura-masaki\$ hirano-atsuo\$ tadano-Hiroshi\$ kachi-tetsu\$ hosokawa-hideki\$).in. and (mirror reflect\$)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 08:49
10	213	(uemura-toshiya\$ nagasaka-naohisa\$ hashimura-masaki\$ hirano-atsuo\$ tadano-Hiroshi\$ kachi-tetsu\$ hosokawa-hideki\$).in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 09:07
13	1	("6335212").PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 09:08
14	2	("5476884" "5514627").PN.	USPAT	2002/08/31 09:08
15	241	(al aluminum) SAME (contact electrode) same (passivat\$ oxide) and gan	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 09:10
-	1285	(257/98).CCLS.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/29 10:43

-	828963	reflect\$3 mirror	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/29 10:43
-	735	((257/98).CCLS.) and (reflect\$3 mirror)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/29 11:31
-	8	("5217564" "5502316" "5620557" "5641381" "5679152" "5804834" "5846844" "6046465").PN.	USPAT	2002/08/29 10:59
-	2	(("5952681") or ("6121636")).PN.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/30 00:07
-	1	6121636.URPN.	USPAT	2002/08/29 11:36
-	3	("3813587" "5798537" "5868951").PN.	USPAT	2002/08/29 11:36
-	2	5952681.URPN.	USPAT	2002/08/29 11:40
-	2	("5650641" "5739552").PN.	USPAT	2002/08/29 11:40
-	4	("4857415" "5641582" "5828088" "5977604").PN.	USPAT	2002/08/29 13:01
-	3	("4396929" "4408217" "4608581").PN.	USPAT	2002/08/29 13:14
-	5	("5146465" "5226053" "5247533" "5369289" "5493577").PN.	USPAT	2002/08/29 13:34
-	4	5862167.URPN.	USPAT	2002/08/29 13:34
-	16	("4445132" "4447822" "4553154" "4875088" "5181220" "5281830" "5483105" "5554877" "5571391" "5587609" "5652438" "5701035" "5798537" "5862167" "5864171" "5905275").PN.	USPAT	2002/08/29 13:38
-	1	6201265.URPN.	USPAT	2002/08/29 13:41
-	0	(stelgerwald-daniel).in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/30 00:08
-	2	(stelgerwald-daniel\$).in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/30 00:10
-	297	(martin-paul\$ rudaz-serge\$ imler-william\$).in.	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/30 00:11
-	79	(martin-paul\$ rudaz-serge\$ imler-william\$).in. and light	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/30 00:18
-	1	(led same chip) and die near5 epoxy with (corrosion barrier)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/30 00:20
-	1	(led same lamp) and die near5 epoxy with (corrosion barrier)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/30 00:20
-	1	(led and chip) and die near5 epoxy with (corrosion barrier)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/30 00:20
-	7	dice and die near5 epoxy with (corrosion barrier)	USPAT; US-PGPUB; EPO; JPO; IBM_TDB	2002/08/31 07:45

-	4	5895966.URPN.	USPAT	2002/08/30 00:23
-	8	("5095359" "5196725" "5220195" "5311057" "5366931" "5386141" "5468994" "5508556").PN.	USPAT	2002/08/30 00:23